

Title (en)

METHOD FOR PASSIVATING METALLIC SUBSTRATES

Title (de)

VERFAHREN ZUR PASSIVIERUNG METALLISCHER SUBSTRATE

Title (fr)

PROCÉDÉ DE PASSIVATION DE SUBSTRATS MÉTALLIQUES

Publication

EP 3771749 A1 20210203 (DE)

Application

EP 19188901 A 20190729

Priority

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Abstract (en)

[origin: MX2020007981A] The present invention relates to a method for adjusting a passivation composition by determining the redox potential of a passivation composition as well as to a method for passivating metallic substrates by treatment with a passivation composition.

Abstract (de)

Die vorliegende Erfindung betrifft ein Verfahren zur Einstellung einer Passivierungszusammensetzung durch Bestimmung des Redoxpotentials Passivierungszusammensetzung sowie ein Verfahren zur Passivierung von metallischen Substraten durch Behandlung mit einer Passivierungszusammensetzung.

IPC 8 full level

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Citation (search report)

- [X] WO 9314241 A1 19930722 - HENKEL CORP [US]
- [X] WO 2004020700 A1 20040311 - HENKEL KGAA [DE], et al
- [X] JP 2006013158 A 20060112 - NAGASE & CO LTD, et al
- [X] JP 2009249736 A 20091029 - MITSUBISHI PAPER MILLS LTD
- [X] EP 3428314 A1 20190116 - DOERKEN EWALD AG [DE]
- [X] DE 102006040908 A1 20080306 - HILLEBRAND WALTER GMBH & CO KG [DE]

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EP 19188901 A 20190729; CN 202010744639 A 20200729; KR 20200093730 A 20200728; MX 2020007981 A 20200729; US 202016940820 A 20200728